

IN THE CLAIMS:

Please amend claims 1, 2, 3 and 5-8 as follows. Attached hereto is a marked-up copy of the amended claims.

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1. (Amended) A method of manufacturing a nitride semiconductor substrate, comprising:

a first step of selectively forming a raised and recessed region in the upper portion of a base substrate;

a second step of growing a semiconductor layer of nitride on said raised and recessed region in said upper portion of said base substrate so that a recessed portion in said raised and recessed region is filled and the upper surface thereof is even; and

01 a third step of irradiating an interface between said semiconductor layer and said base substrate with a laser beam, thereby separating said semiconductor layer from said base substrate to form a semiconductor substrate from said semiconductor layer.

2. (Amended) The method of manufacturing a nitride semiconductor substrate according to claim 1, wherein in said third step, the laser beam is irradiated upon at least a raised portion in said raised and recessed region.

3. (Amended) A method of manufacturing a nitride semiconductor substrate, comprising:

a first step of selectively forming an irregular region on the main surface of a base substrate;

a second step of growing a semiconductor layer of nitride on said irregular region in said base substrate so that a recessed portion in the irregular region is filled and the upper surface thereof is even; and

a third step of irradiating an interface between said semiconductor layer and said base substrate with a laser beam, thereby separating said semiconductor layer from said base substrate to form a semiconductor substrate from said semiconductor layer,

Q1 wherein in said first step, a plurality of grooves extending parallel to each other are formed on said main surface of said base substrate, and

wherein in said third step, the laser beam is irradiated upon at least a raised portion in said irregular region while scanning along raised portions surrounded by said plurality of grooves in said base substrate.

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5. (Amended) A method of manufacturing a nitride semiconductor substrate, comprising:

a first step of selectively forming an irregular region on the main surface of a base substrate;

a second step of growing a semiconductor layer of nitride on said irregular region in said base substrate so that a recessed portion in the irregular region is filled and the upper surface thereof is even; and

Q2 a third step of irradiating an interface between said semiconductor layer and said base substrate with a laser beam, thereby separating said semiconductor layer from said base substrate to form a semiconductor substrate from said semiconductor layer,

wherein in said first step, a plurality of island shaped raised portions are formed on the main surface of said base substrate, and

wherein in said third step, a pulsed laser beam is irradiated upon at least a raised portion in said irregular region while scanning in synchronization with said plurality of raised portions in said base substrate.

6. (Amended) A method of manufacturing a nitride semiconductor substrate, comprising:

a first step of selectively forming an irregular region on the main surface of a base substrate;

a second step of growing a semiconductor layer of nitride on said irregular region in said base substrate so that a recessed portion in the irregular region is filled and the upper surface thereof is even; and

a third step of irradiating an interface between said semiconductor layer and said base substrate with a laser beam, thereby separating said semiconductor layer from said based substrate to form a semiconductor substrate from said semiconductor layer,

wherein in said third step, the laser beam is irradiated simultaneously upon the plurality of raised portions in said irregular region.

7. (Amended) A method of manufacturing a nitride semiconductor substrate, comprising:


a first step of selectively forming an irregular region on the main surface of a base substrate;

a second step of growing a semiconductor layer of nitride on said irregular region in said base substrate so that a recessed portion in the irregular region is filled and the upper surface thereof is even; and

a third step of irradiating an interface between said semiconductor layer and said base substrate with a laser beam, thereby separating said semiconductor layer from said based substrate to form a semiconductor substrate from said semiconductor layer,

wherein in said first step, the area occupied by the recessed portions is about in the range from about 1/5 to about 100 times the area occupied by the raised portions.

8. (Amended) A method of manufacturing a nitride semiconductor substrate, comprising:

 a first step of selectively forming an irregular region on the main surface of a base substrate;

a second step of growing a semiconductor layer of nitride on said irregular region in said base substrate so that a recessed portion in the irregular region is filled and the upper surface thereof is even; and

a third step of irradiating an interface between said semiconductor layer and said base substrate with a laser beam, thereby separating said semiconductor layer from said based substrate to form a semiconductor substrate from said semiconductor layer,

wherein in said third step, the laser beam is irradiated from the surface opposite to the main surface of said base substrate.

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